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(54) METHOD AND APPARATUS FOR REDUCING THE MECHANICAL STRESS WHEN MOUNTING ASSEMBLIES WITH THERMAL PADS

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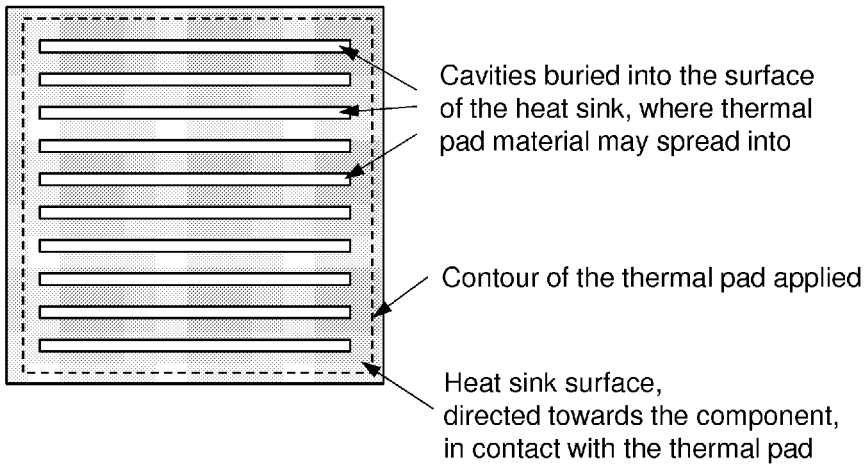
(57) **ABSTRACT**

It is provided a device and method for mounting of a heat sink on a printed circuit board with one or more electronic components to be cooled reducing the mechanical stress on the electronic components and the printed circuit board. The thermal contact between the heat sink and the electronic components to be cooled is formed by a thermal pad. The surface of the heat sink which is in contact with the thermal pad has at least one cavity into which the thermal pad can spread when the electronic component and the heat sink are pressed against each other thereby compressing the thermal pad.



Inventive design: Material is carved out of the heat sink